

**What Is Claimed Is:**

- 1           1.       An integrated circuit assembly module, comprising:  
2           a first substrate, with a front face and a back face opposite the front face;  
3           a first semiconductor die with an active face upon which active circuitry  
4   and signal pads reside, and a back face opposite the active face;  
5           a second semiconductor die with an active face upon which active circuitry  
6   and signal pads reside, and a back face opposite the active face;  
7           a second substrate, with a front face and a back face opposite the front  
8   face;  
9           wherein the first semiconductor die and the second semiconductor die are  
10   arranged active face to active face so that signal pads on the first semiconductor  
11   die overlap with signal pads on the second semiconductor die, thereby facilitating  
12   capacitive communication between the first semiconductor die and the second  
13   semiconductor die; and  
14           wherein the first semiconductor die and the second semiconductor die are  
15   pressed together between the first substrate and the second substrate so that the  
16   front face of the first substrate is in contact with the back face of the first  
17   semiconductor die and the front face of the second substrate is in contact with the  
18   back face of the second semiconductor die.
- 1           2.       The integrated circuit assembly module of claim 1, further  
2   comprising:  
3           a first heat removal mechanism coupled to the back face of the first  
4   substrate; and  
5           a second heat removal mechanism coupled to the back face of the second  
6   substrate.

1           3.       The integrated circuit assembly module of claim 2, wherein the  
2 first and second heat removal mechanisms include cooling fins to facilitate the  
3 transfer of heat to air passing across the cooling fins.

1           4.       The integrated circuit assembly module of claim 2, wherein the  
2 first and second heat removal mechanisms include graphite foam or metal with  
3 fin-like structures which facilitate in the transfer of heat to a liquid pumped  
4 through the graphite foam or metal.

1           5.       The integrated circuit assembly module of claim 1, further  
2 comprising:  
3           a first power supply coupled to the back face of the first substrate; and  
4           a second power supply coupled to the back face of the second substrate.

1           6.       The integrated circuit assembly module of claim 1, wherein the  
2 first and second substrates include metal layers that supply power to the first and  
3 second semiconductor dies.

1           7.       The integrated circuit assembly module of claim 6, wherein the  
2 first and second substrates include power connectors on the back faces of the first  
3 and second substrates.

1           8.       The integrated circuit assembly module of claim 6, further  
2 comprising Micro Electro-Mechanical System (MEMS) spring contacts that  
3 provide power from the metal layers within the first and second substrates to the  
4 first and second semiconductor dies, wherein:

5           a first set of MEMS spring contacts on the front face of the first substrate  
6   contact the active side of the second semiconductor die; and  
7           a second set of MEMS spring contacts on the front face of the second  
8   substrate contact the active side of the first semiconductor die.

1           9.       The integrated circuit assembly module of claim 6, further  
2   comprising:

3           a first power regulator incorporated within the first substrate; and  
4           a second power regulator incorporated within the second substrate.

1           10.      The integrated circuit assembly module of claim 1, further  
2   comprising:

3           an I/O semiconductor die with an active face upon which active circuitry  
4   and signal pads reside, and a back face opposite the active face;

5           wherein the I/O semiconductor die and the second semiconductor die are  
6   arranged active face to active face, so that signal pads on the I/O semiconductor  
7   die overlap with signal pads on the second semiconductor die, thereby facilitating  
8   capacitive communication between the I/O semiconductor die and the second  
9   semiconductor die;

10          wherein the I/O semiconductor die is located on an edge of the first  
11   substrate to facilitate in providing communications into and out of the integrated  
12   circuit assembly module; and

13          wherein the edge of the first substrate extends beyond the edge of the  
14   second substrate so that a portion of the active face of the I/O semiconductor die is  
15   exposed to facilitate external connections.

1           11.     The integrated circuit assembly module of claim 10, further  
2     comprising optical external connection pads located on the exposed portion of the  
3     active side of the I/O semiconductor die.

1           12.     The integrated circuit assembly module of claim 10, further  
2     comprising electrical external connection pads located on the exposed portion of  
3     the active side of the I/O semiconductor die.

1           13.     A method for fabricating an integrated circuit assembly module,  
2     comprising:  
3             arranging a first semiconductor die and a second semiconductor die active  
4     face to active face such that signal pads on the first semiconductor die overlap  
5     with signal pads on the second semiconductor die, thereby facilitating capacitive  
6     communication between the first semiconductor die and the second  
7     semiconductor die, and wherein the first and second semiconductor dies comprise  
8     an active face upon which active circuitry and signal pads reside, and a back face  
9     opposite the active face; and  
10            pressing together the first semiconductor die and the second  
11     semiconductor die between a first substrate and a second substrate such that the  
12     first substrate is in contact with the back face of the first semiconductor die and  
13     the second substrate is in contact with the back face of the second semiconductor  
14     die.

1           14.     The method of claim 13, wherein the integrated circuit assembly  
2     module further comprises:  
3             a first heat removal mechanism coupled to the opposite side of the first  
4     substrate from the first semiconductor die; and

5           a second heat removal mechanism coupled to the opposite side of the  
6   second substrate from the second semiconductor die.

1           15.    The method of claim 14, wherein the first and second heat removal  
2   mechanisms include cooling fins to facilitate the transfer of heat to air blown  
3   across the cooling fins.

1           16.    The method of claim 14, wherein the first and second heat removal  
2   mechanisms include graphite foam or metal with fin-like structures which  
3   facilitate in the transfer of heat to a liquid pumped through the graphite foam or  
4   metal.

1           17.    The method of claim 13, wherein the integrated circuit assembly  
2   module further comprises:  
3           a first power supply coupled to the opposite side of the first substrate from  
4   the first semiconductor die; and  
5           a second power supply coupled to the opposite side of the second substrate  
6   from the second semiconductor die.

1           18.    The method of claim 13, wherein the first and second substrates  
2   include metal layers that facilitate in supplying power to the first and second  
3   semiconductor dies.

1           19.    The method of claim 18, wherein the first and second substrates  
2   include power connectors on the opposite sides of the first and second substrates  
3   from the first and second semiconductor dies.

1           20.     The method of claim 18, wherein the integrated circuit assembly  
2 module further comprises Micro Electro-Mechanical System (MEMS) spring  
3 contacts that facilitate in providing power from the metal layers within the first  
4 and second substrates to the first and second semiconductor dies, wherein:  
5           a first plurality of MEMS spring contacts attached to the semiconductor  
6 die side of the first substrate that contact the active side of the second  
7 semiconductor die; and  
8           a second plurality of MEMS spring contacts attached to the semiconductor  
9 die side of the second substrate that contact the active side of the first  
10 semiconductor die.

1           21.     The method of claim 18, wherein the integrated circuit assembly  
2 module further comprises:  
3           a first power regulator incorporated within the first substrate; and  
4           a second power regulator incorporated within the second substrate.

1           22.     The method of claim 13, wherein the integrated circuit assembly  
2 module further comprises:  
3           an I/O semiconductor die with an active face upon which active circuitry -  
4 including signal pads - resides, and a back face opposite the active face;  
5           wherein the I/O semiconductor die and the second semiconductor die are  
6 arranged active face to active face such that signal pads on the I/O semiconductor  
7 die overlap with signal pads on the second semiconductor die, thereby facilitating  
8 capacitive communication between the I/O semiconductor die and the second  
9 semiconductor die;

10            wherein the I/O semiconductor die is located on the edge of the first  
11     substrate to facilitate in providing communications in and out of the integrated  
12     circuit assembly module; and

13            wherein the edge of the first substrate extends beyond the edge of the  
14     second substrate such that a portion of the active face of the I/O semiconductor  
15     die is exposed to facilitate external connections.

1            23.     The method of claim 10, wherein the integrated circuit assembly  
2     module further comprises optical external connection pads located on the exposed  
3     portion of the active side of the I/O semiconductor die.

1            24.     The method of claim 10, wherein the integrated circuit assembly  
2     module further comprises electrical external connection pads located on the  
3     exposed portion of the active side of the I/O semiconductor die.

1            25.     A computer system comprising an integrated circuit assembly  
2     module, comprising:  
3            a first substrate, with a front face and a back face opposite the front face;  
4            a first semiconductor die with an active face upon which active circuitry  
5     and signal pads reside, and a back face opposite the active face;  
6            a second semiconductor die with an active face upon which active circuitry  
7     and signal pads reside, and a back face opposite the active face;  
8            a second substrate, with a front face and a back face opposite the front  
9     face;  
10           wherein the first semiconductor die and the second semiconductor die are  
11     arranged active face to active face so that signal pads on the first semiconductor  
12     die overlap with signal pads on the second semiconductor die, thereby facilitating

13 capacitive communication between the first semiconductor die and the second  
14 semiconductor die; and  
15 wherein the first semiconductor die and the second semiconductor die are  
16 pressed together between the first substrate and the second substrate so that the  
17 front face of the first substrate is in contact with the back face of the first  
18 semiconductor die and the front face of the second substrate is in contact with the  
19 back face of the second semiconductor die.

1 26. The computer system of claim 25, wherein the integrated circuit  
2 assembly module further comprises:  
3 a first heat removal mechanism coupled to the back face of the first  
4 substrate; and  
5 a second heat removal mechanism coupled to the back face of the second  
6 substrate.

1 27. The computer system of claim 26, wherein the first and second  
2 heat removal mechanisms include cooling fins to facilitate the transfer of heat to  
3 air passing across the cooling fins.

1 28. The computer system of claim 26, wherein the first and second  
2 heat removal mechanisms include graphite foam or metal with fin-like structures  
3 which facilitate in the transfer of heat to a liquid pumped through the graphite  
4 foam or metal.

1 29. The computer system of claim 25, further comprising:  
2 a first power supply coupled to the back face of the first substrate; and



3 a second power supply coupled to the back face of the second substrate.

1 30. The computer system of claim 25, wherein the first and second  
2 substrates include metal layers that supply power to the first and second  
3 semiconductor dies.

1 31. The computer system of claim 30, wherein the first and second  
2 substrates include power connectors on the back faces of the first and second  
3 substrates.

1 32. The computer system of claim 30, wherein the integrated circuit  
2 assembly module further comprises Micro Electro-Mechanical System (MEMS)  
3 spring contacts that provide power from the metal layers within the first and  
4 second substrates to the first and second semiconductor dies, wherein:  
5 a first set of MEMS spring contacts on the front face of the first substrate  
6 contact the active side of the second semiconductor die; and  
7 a second set of MEMS spring contacts on the front face of the second  
8 substrate contact the active side of the first semiconductor die.

1 33. The computer system of claim 30, wherein the integrated circuit  
2 assembly module further comprises:  
3 a first power regulator incorporated within the first substrate; and  
4 a second power regulator incorporated within the second substrate.

1 34. The computer system of claim 25, wherein the integrated circuit  
2 assembly module further comprises:

3           an I/O semiconductor die with an active face upon which active circuitry  
4   and signal pads reside, and a back face opposite the active face;  
5           wherein the I/O semiconductor die and the second semiconductor die are  
6   arranged active face to active face, so that signal pads on the I/O semiconductor  
7   die overlap with signal pads on the second semiconductor die, thereby facilitating  
8   capacitive communication between the I/O semiconductor die and the second  
9   semiconductor die;  
10          wherein the I/O semiconductor die is located on an edge of the first  
11   substrate to facilitate in providing communications into and out of the integrated  
12   circuit assembly module; and  
13          wherein the edge of the first substrate extends beyond the edge of the  
14   second substrate so that a portion of the active face of the I/O semiconductor die is  
15   exposed to facilitate external connections.

1           35.    The computer system of claim 34, wherein the integrated circuit  
2   assembly module further comprises optical external connection pads located on  
3   the exposed portion of the active side of the I/O semiconductor die.

1           36.    The computer system of claim 34, wherein the integrated circuit  
2   assembly module further comprises electrical external connection pads located on  
3   the exposed portion of the active side of the I/O semiconductor die.